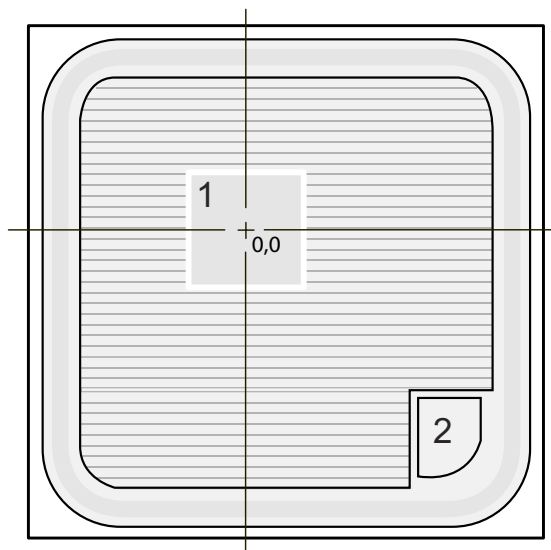


Pad Layout



Backside: Drain

Die Specifications

Device	Die Dimensions			Back Side Metal	Back Side	Bonding Pad Material
	Length ¹ (mils)	Width ¹ (mils)	Thickness (mils)			
TP0604	55	55	11 ± 1.5	Au	Drain	Al/Cu/Si

Bonding Pad Description

Pad #	Function	x Position ² (mils)	y Position ² (mils)	x Size (mils)	y Size (mils)
1	Source	0	0	11.8	11.8
2	Gate	21.8	-22.4	5.9	7.6

Notes:

1. Maximum values.
2. Position referenced to center of pad.

Supertex inc. does not recommend the use of its products in life support applications, and will not knowingly sell them for use in such applications unless it receives an adequate "product liability indemnification insurance agreement." **Supertex inc.** does not assume responsibility for use of devices described, and limits its liability to the replacement of the devices determined defective due to workmanship. No responsibility is assumed for possible omissions and inaccuracies. Circuitry and specifications are subject to change without notice. For the latest product specifications refer to the **Supertex inc.** (website: <http://www.supertex.com>)